

ABSTRACT

The present invention relates to a method of combining components to form an integrated device, wherein at least one first component is provided on a first surface of a sacrificial substrate, and at least one second component is provided on a first surface of a non-sacrificial substrate. At least one support structure is formed on at least one of said first surfaces of said sacrificial substrate, and said non-sacrificial substrate, respectively, such that said at least one support structure is extended outwardly from at least one of said first surfaces. The sacrificial substrate carrying said at least one first component, and said non-sacrificial substrate carrying said at least one second component, respectively, is bonded with an intermediate bonding material, so that said first and second surfaces will be facing one another with a distance defined by a thickness of said support structure. At least a part of said sacrificial substrate is removed. The at least one first component and said at least one second component is interconnected.